

# C2M1000170D

**Silicon Carbide Power MOSFET**  
**C2M™ MOSFET Technology**  
 N-Channel Enhancement Mode

$V_{DS}$	1700 V
$I_D @ 25^\circ\text{C}$	5.0 A
$R_{DS(on)}$	1.0 $\Omega$

## Features

- High Speed Switching with Low Capacitances
- High Blocking Voltage with Low  $R_{DS(on)}$
- Easy to Parallel and Simple to Drive
- Ultra-low Drain-gate capacitance
- Halogen Free, RoHS Compliant

## Benefits

- Higher System Efficiency
- Increased System Switching Frequency
- Reduced Cooling Requirements
- Increased System Reliability

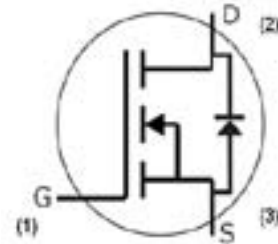
## Applications

- Auxiliary Power Supplies
- Switch Mode Power Supplies
- High-voltage Capacitive Loads

## Package



TO-247-3



Part Number	Package
C2M1000170D	TO-247-3

## Maximum Ratings ( $T_c = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Value	Unit	Test Conditions	Note
$V_{DSmax}$	Drain - Source Voltage	1700	V	$V_{GS} = 0\text{ V}, I_D = 100\ \mu\text{A}$	
$V_{GSmax}$	Gate - Source Voltage	-10/+25	V	Absolute maximum values	
$V_{GSop}$	Gate - Source Voltage	-5/+20	V	Recommended operational values	
$I_D$	Continuous Drain Current	5.0	A	$V_{GS} = 20\text{ V}, T_C = 25^\circ\text{C}$	Fig. 19
		3.5		$V_{GS} = 20\text{ V}, T_C = 100^\circ\text{C}$	
$I_{D(pulse)}$	Pulsed Drain Current	6.0	A	Pulse width $t_p$ limited by $T_{jmax}$	Fig. 22
$P_D$	Power Dissipation	69	W	$T_c = 25^\circ\text{C}, T_j = 150^\circ\text{C}$	Fig. 20
$T_J, T_{stg}$	Operating Junction and Storage Temperature	-55 to +150	$^\circ\text{C}$		
$T_L$	Solder Temperature	260	$^\circ\text{C}$	1.6mm (0.063") from case for 10s	
$M_d$	Mounting Torque	1	Nm lbf-in	M3 or 6-32 screw	
		8.8			

**Electrical Characteristics** ( $T_c = 25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions	Note
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	1700			V	$V_{GS} = 0\text{ V}, I_D = 100\ \mu\text{A}$	
$V_{GS(th)}$	Gate Threshold Voltage	2.0	2.6	4	V	$V_{DS} = V_{GS}, I_D = 0.5\ \text{mA}$	Fig. 11
			2.1		V	$V_{DS} = V_{GS}, I_D = 0.5\ \text{mA}, T_J = 150^\circ\text{C}$	
$I_{DSS}$	Zero Gate Voltage Drain Current		1	100	$\mu\text{A}$	$V_{DS} = 1.7\ \text{kV}, V_{GS} = 0\ \text{V}$	
$I_{GSS}$	Gate-Source Leakage Current			250	nA	$V_{GS} = 20\ \text{V}, V_{DS} = 0\ \text{V}$	
$R_{DS(on)}$	Drain-Source On-State Resistance		1.0	1.4	$\Omega$	$V_{GS} = 20\ \text{V}, I_D = 2\ \text{A}$	Fig. 4,5,6
			2.0			$V_{GS} = 20\ \text{V}, I_D = 2\ \text{A}, T_J = 150^\circ\text{C}$	
$g_{fs}$	Transconductance		0.82		S	$V_{DS} = 20\ \text{V}, I_{DS} = 2\ \text{A}$	Fig. 7
			0.81			$V_{DS} = 20\ \text{V}, I_{DS} = 2\ \text{A}, T_J = 150^\circ\text{C}$	
$C_{iss}$	Input Capacitance		200		pF	$V_{GS} = 0\ \text{V}$ $V_{DS} = 1000\ \text{V}$ $f = 1\ \text{MHz}$	Fig. 17,18
$C_{oss}$	Output Capacitance		12				
$C_{riss}$	Reverse Transfer Capacitance		1.3				
$E_{oss}$	$C_{oss}$ Stored Energy		7		$\mu\text{J}$	$V_{AC} = 25\ \text{mV}$	Fig. 16
$E_{ON}$	Turn-On Switching Energy		40		$\mu\text{J}$	$V_{DS} = 1.2\ \text{kV}, V_{GS} = -5/20\ \text{V}$ $I_D = 2\ \text{A}, R_{G(ext)} = 2.5\ \Omega,$ $L = 1478\ \mu\text{H}, T_J = 150^\circ\text{C}$	Fig. 26
$E_{OFF}$	Turn Off Switching Energy		15				
$t_{d(on)}$	Turn-On Delay Time		6		ns	$V_{DD} = 1.2\ \text{kV}, V_{GS} = -5/20\ \text{V}$ $I_D = 2\ \text{A}, R_{G(ext)} = 2.5\ \Omega, R_L = 600\ \Omega$ Timing relative to $V_{DS}$ Per IEC60747-8-4 pg 83	Fig. 27
$t_r$	Rise Time		10.5				
$t_{d(off)}$	Turn-Off Delay Time		11				
$t_f$	Fall Time		60				
$R_{G(int)}$	Internal Gate Resistance		24.8		$\Omega$	$f = 1\ \text{MHz}, V_{AC} = 25\ \text{mV}$	
$Q_{gs}$	Gate to Source Charge		4.7		nC	$V_{DS} = 1.2\ \text{kV}, V_{GS} = -5/20\ \text{V}$ $I_D = 2\ \text{A}$ Per IEC60747-8-4 pg 21	Fig. 12
$Q_{gd}$	Gate to Drain Charge		5.4				
$Q_g$	Total Gate Charge		13				

**Reverse Diode Characteristics**

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
$V_{SD}$	Diode Forward Voltage	3.8		V	$V_{GS} = -5\ \text{V}, I_{SD} = 1\ \text{A}, T_J = 25^\circ\text{C}$	Fig. 8, 9, 10
		3.3		V	$V_{GS} = -5\ \text{V}, I_{SD} = 1\ \text{A}, T_J = 150^\circ\text{C}$	
$I_S$	Continuous Diode Forward Current		4	A	$T_c = 25^\circ\text{C}$	Note 1
$t_{rr}$	Reverse Recovery Time	20		ns	$V_{GS} = -5\ \text{V}, I_{SD} = 2\ \text{A}, T_J = 25^\circ\text{C}$ $V_R = 1.2\ \text{kV}$ $dif/dt = 1200\ \text{A}/\mu\text{s}$	Note 1
$Q_{rr}$	Reverse Recovery Charge	24		nC		
$I_{rrm}$	Peak Reverse Recovery Current	6.5		A		

Note (1): When using SiC Body Diode the maximum recommended  $V_{GS} = -5\text{V}$

**Thermal Characteristics**

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
$R_{\theta JC}$	Thermal Resistance from Junction to Case	1.7	1.8	$^\circ\text{C}/\text{W}$		Fig. 21
$R_{\theta JA}$	Thermal Resistance from Junction to Ambient		40			

## Typical Performance

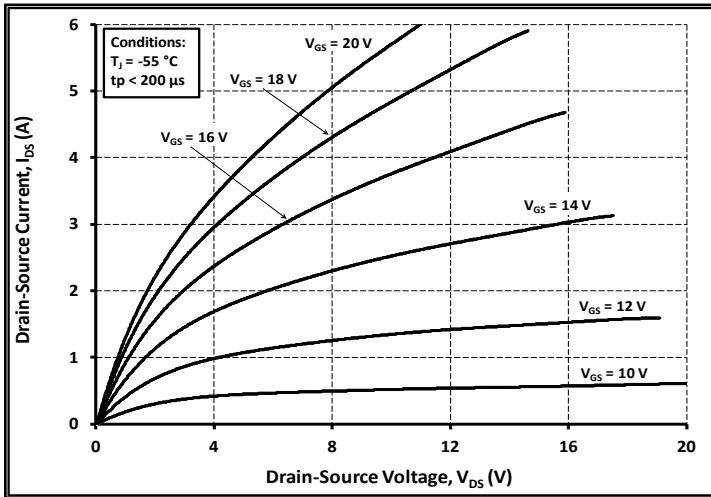


Figure 1. Output Characteristics  $T_j = -55\text{ }^\circ\text{C}$

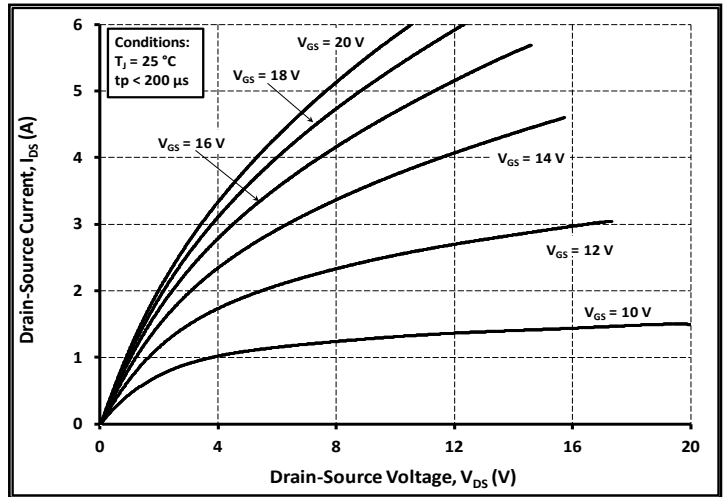


Figure 2. Output Characteristics  $T_j = 25\text{ }^\circ\text{C}$

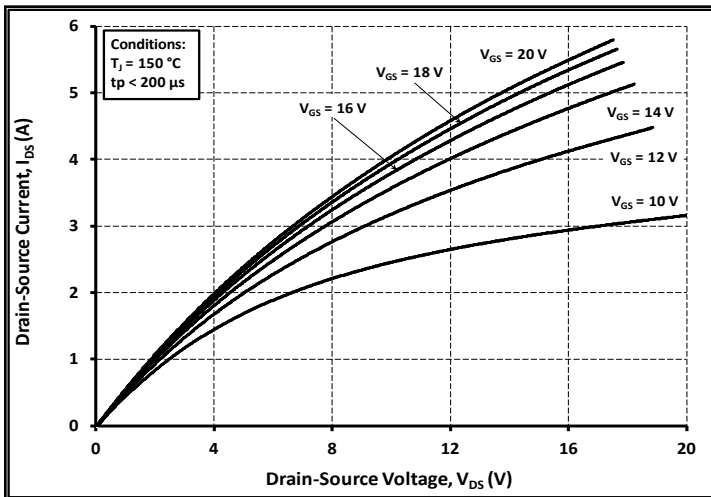


Figure 3. Output Characteristics  $T_j = 150\text{ }^\circ\text{C}$

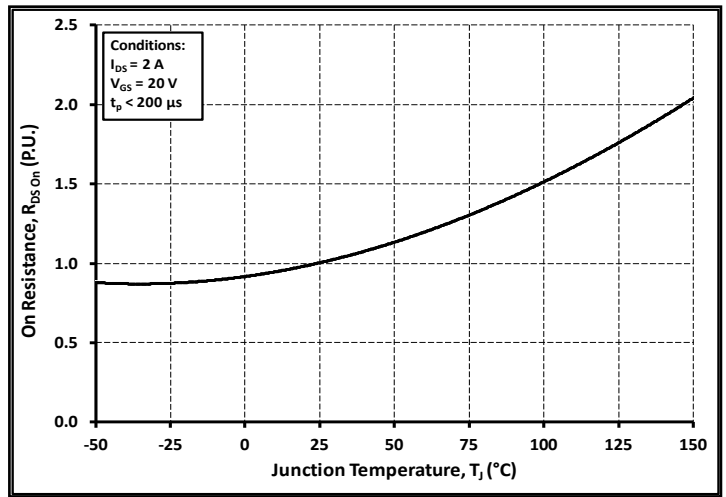


Figure 4. Normalized On-Resistance vs. Temperature

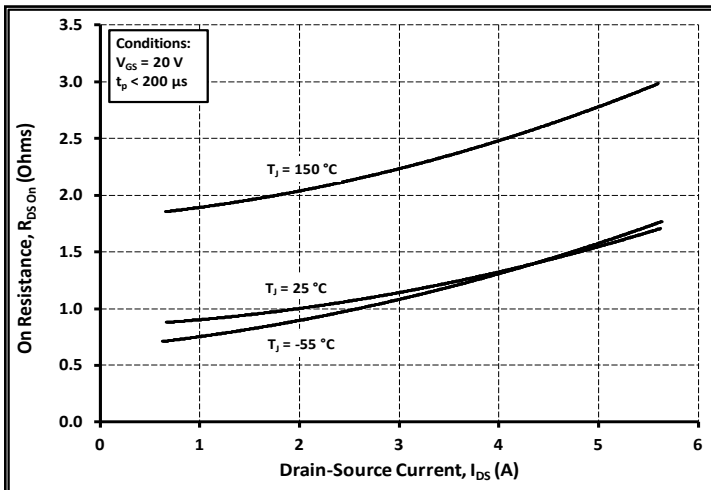


Figure 5. On-Resistance vs. Drain Current For Various Temperatures

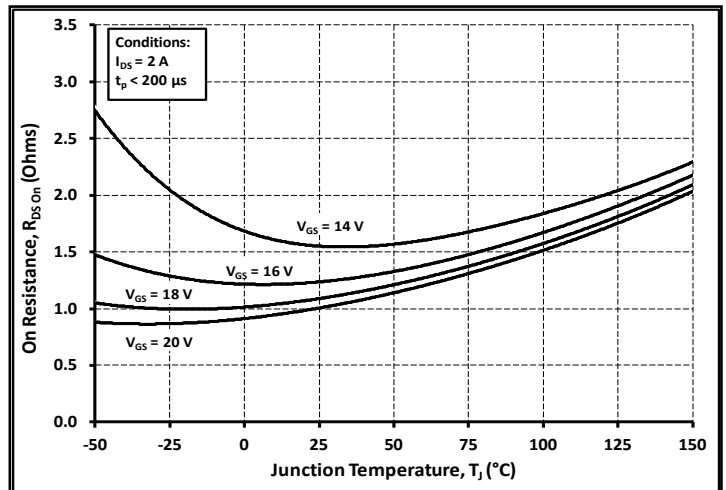


Figure 6. On-Resistance vs. Temperature For Various Gate Voltage

## Typical Performance

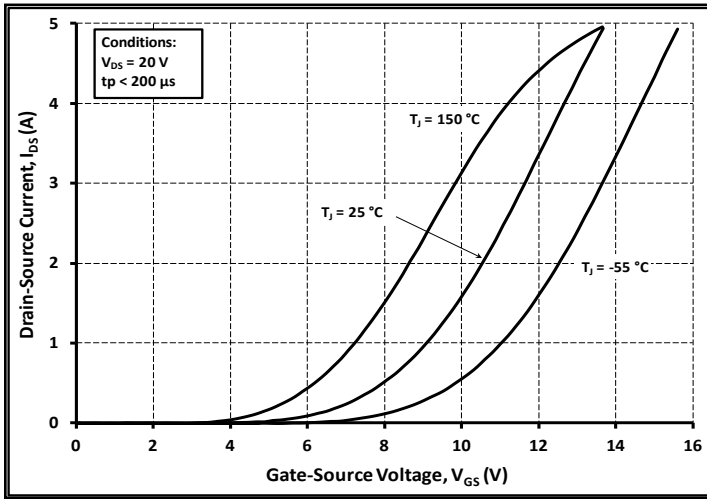


Figure 7. Transfer Characteristic for Various Junction Temperatures

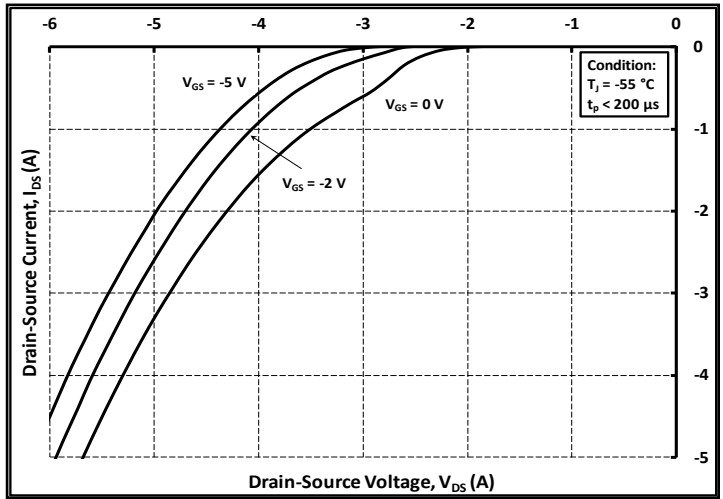


Figure 8. Body Diode Characteristic at  $-55\text{ }^\circ\text{C}$

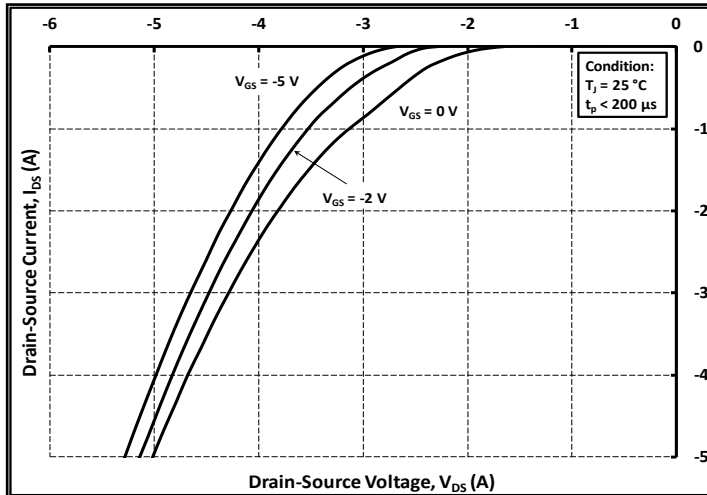


Figure 9. Body Diode Characteristic at  $25\text{ }^\circ\text{C}$

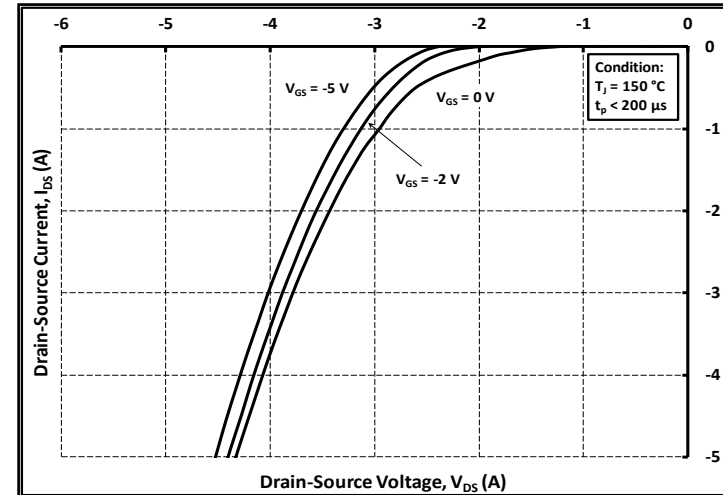


Figure 10. Body Diode Characteristic at  $150\text{ }^\circ\text{C}$

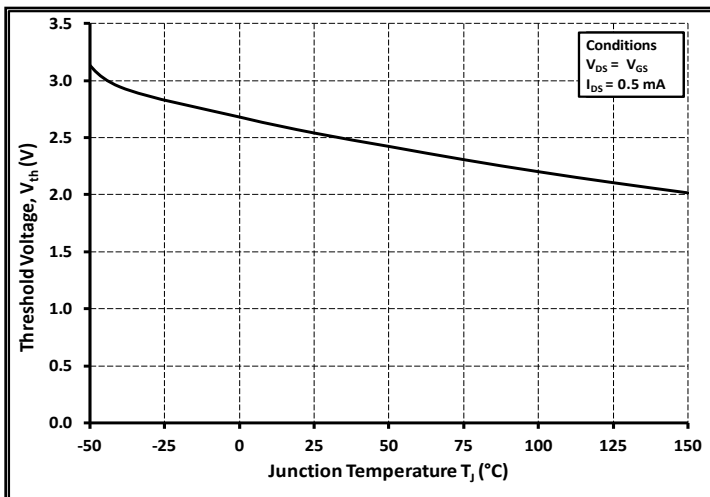


Figure 11. Threshold Voltage vs. Temperature

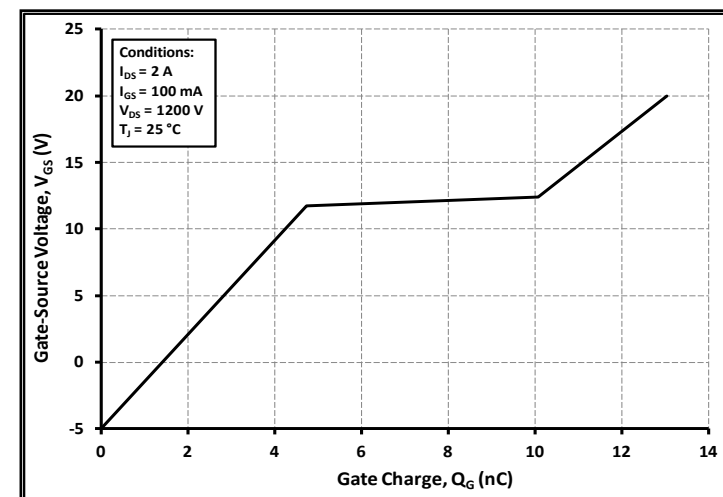


Figure 12. Gate Charge Characteristics

## Typical Performance

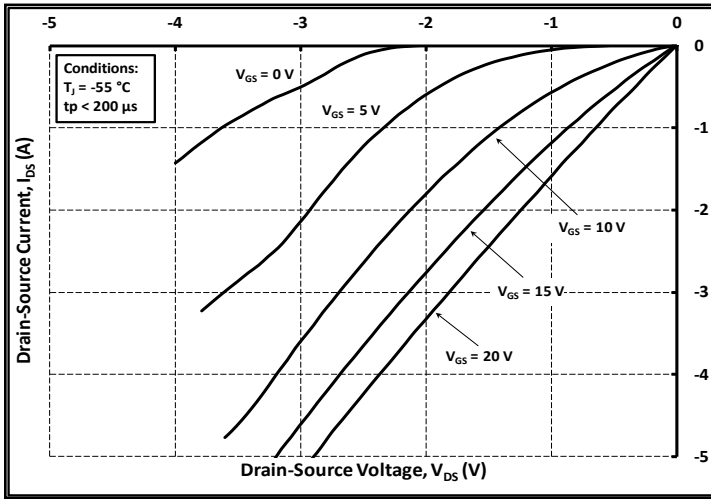


Figure 13. 3rd Quadrant Characteristic at -55 °C

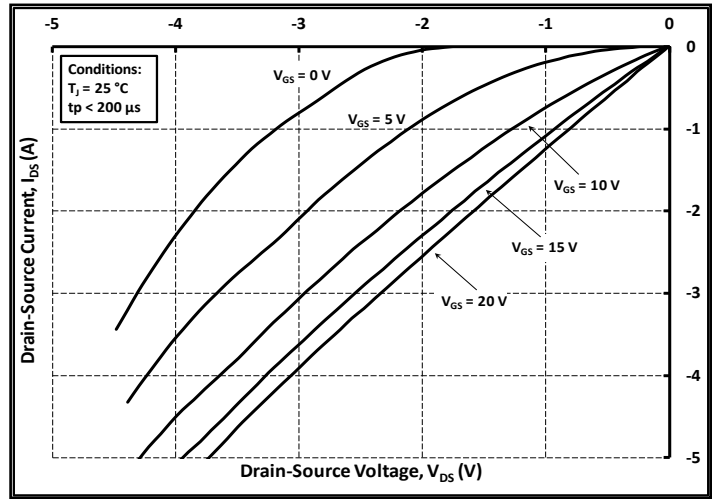


Figure 14. 3rd Quadrant Characteristic at 25 °C

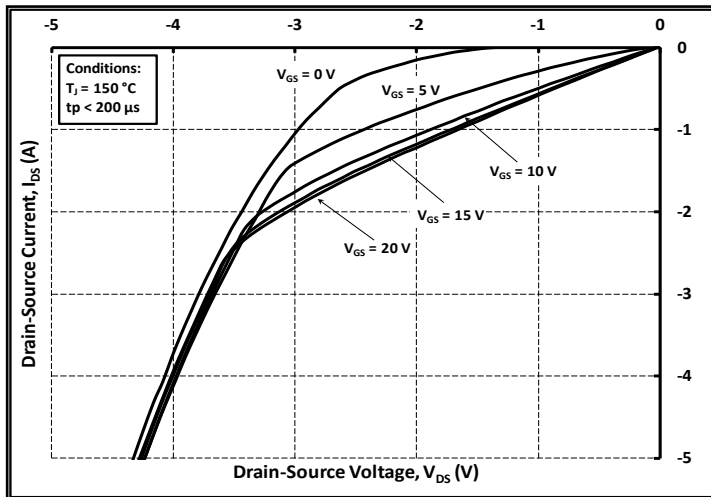


Figure 15. 3rd Quadrant Characteristic at 150 °C

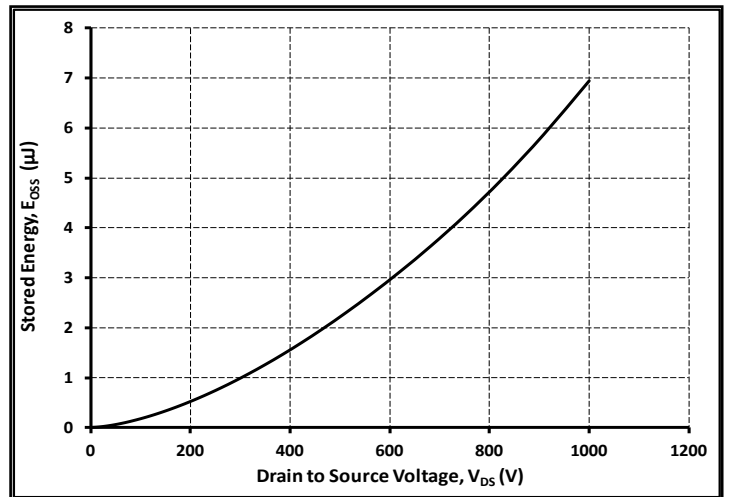


Figure 16. Output Capacitor Stored Energy

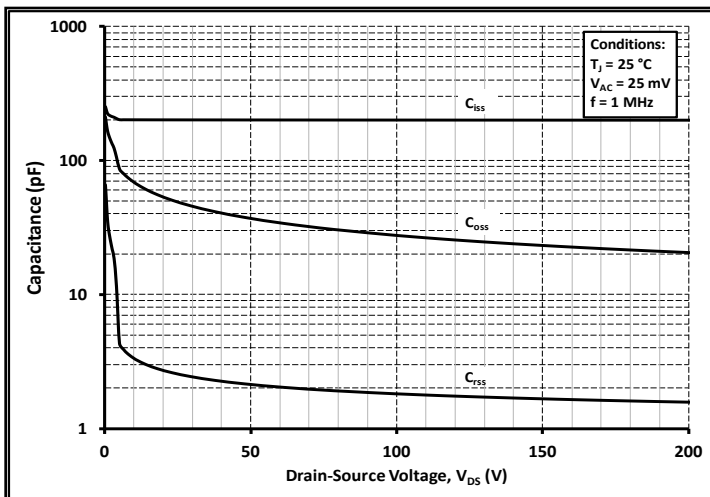


Figure 17. Capacitances vs. Drain-Source Voltage (0-200 V)

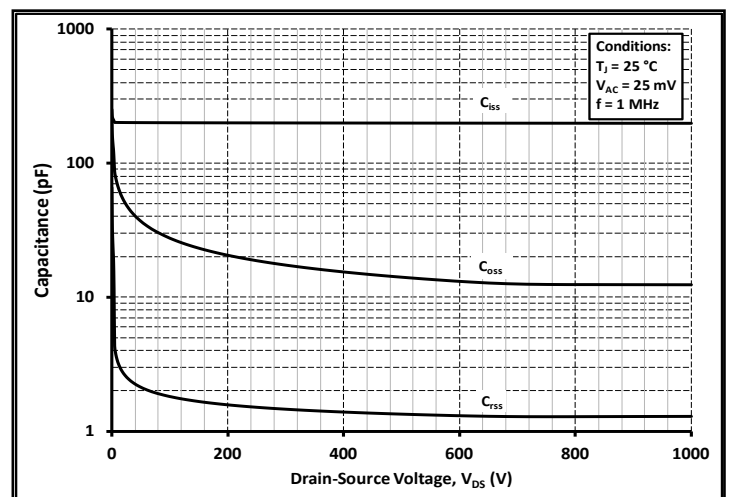


Figure 18. Capacitances vs. Drain-Source Voltage (0-1000 V)

## Typical Performance

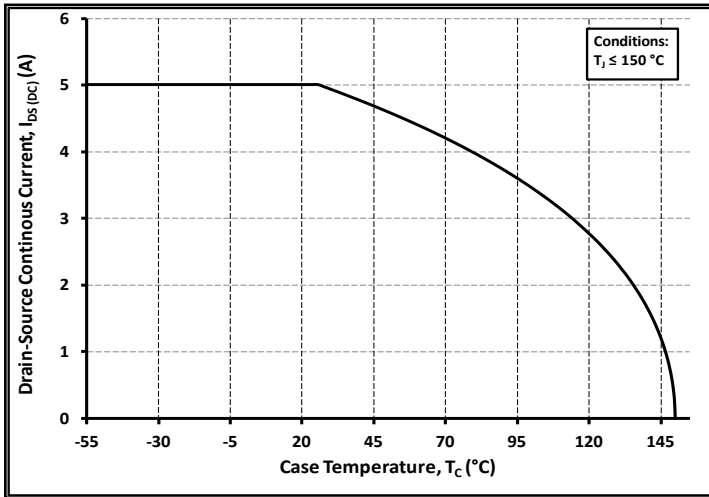


Figure 19. Continuous Drain Current Derating vs. Case Temperature

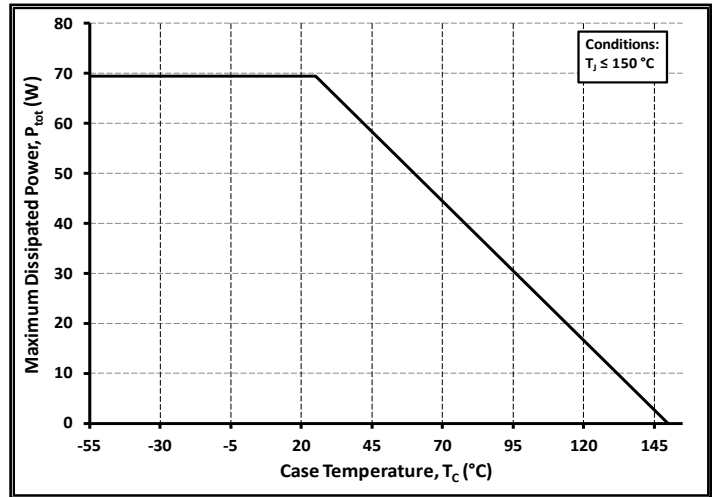


Figure 20. Maximum Power Dissipation Derating vs. Case Temperature

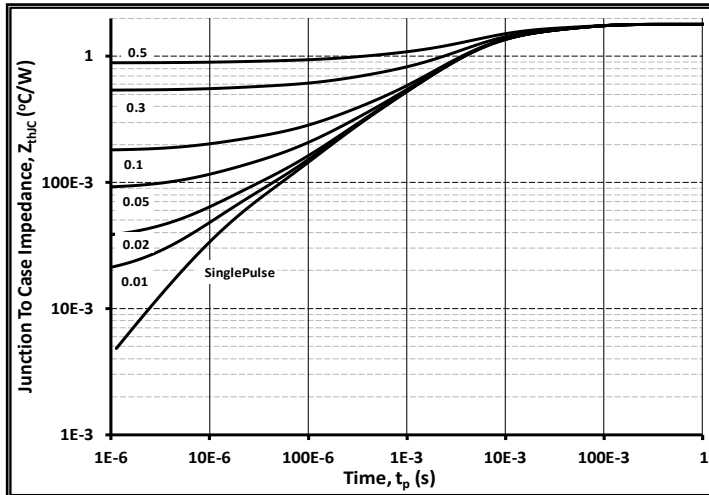


Figure 21. Transient Thermal Impedance (Junction - Case)

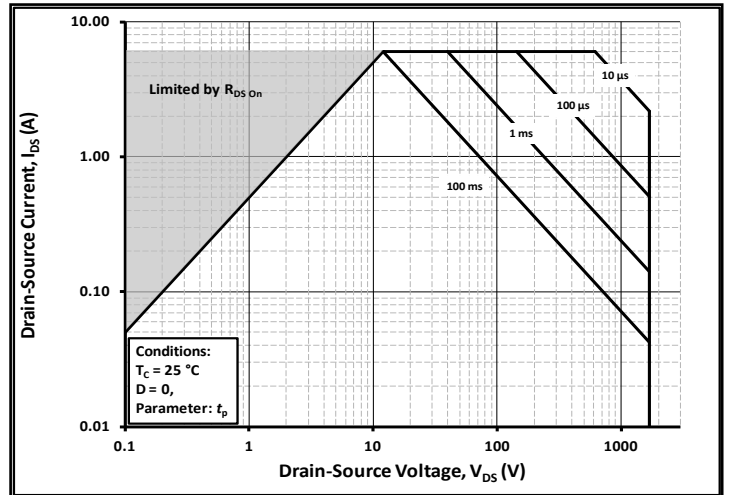


Figure 22. Safe Operating Area

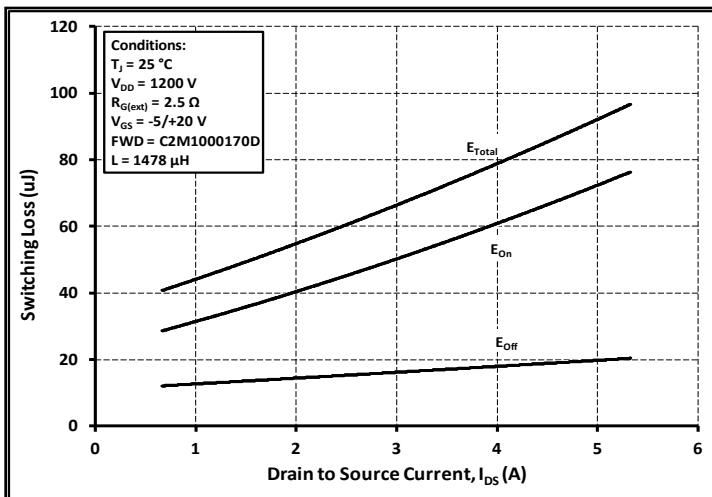


Figure 23. Clamped Inductive Switching Energy vs. Drain Current ( $V_{DD} = 1200 \text{ V}$ )

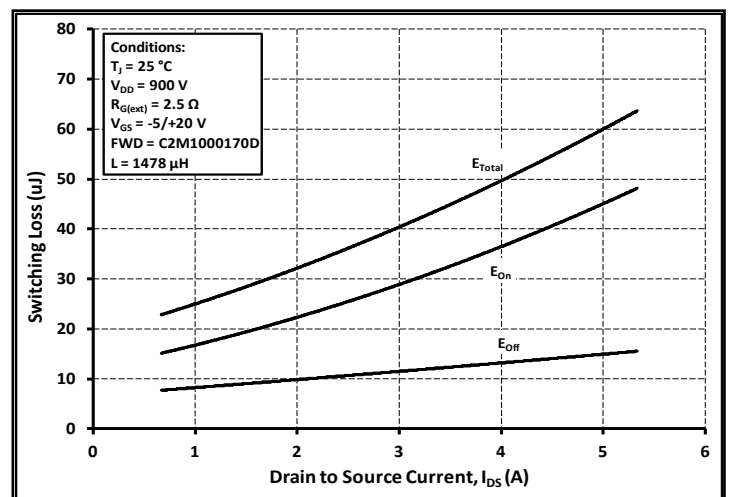


Figure 24. Clamped Inductive Switching Energy vs. Drain Current ( $V_{DD} = 900 \text{ V}$ )

## Typical Performance

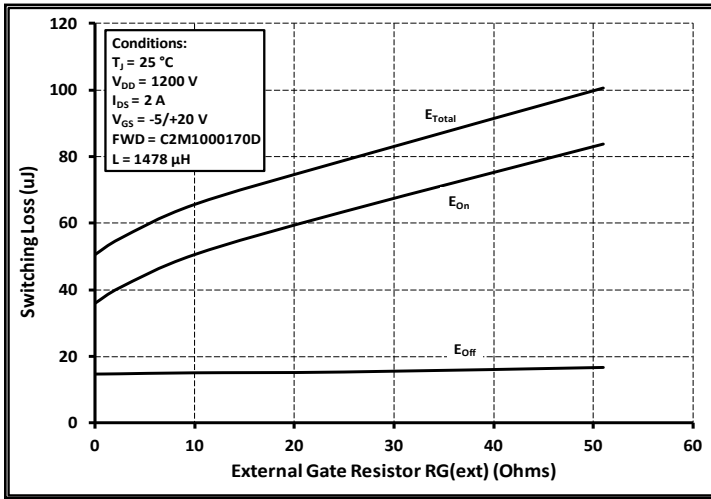


Figure 25. Clamped Inductive Switching Energy vs.  $R_{G(ext)}$

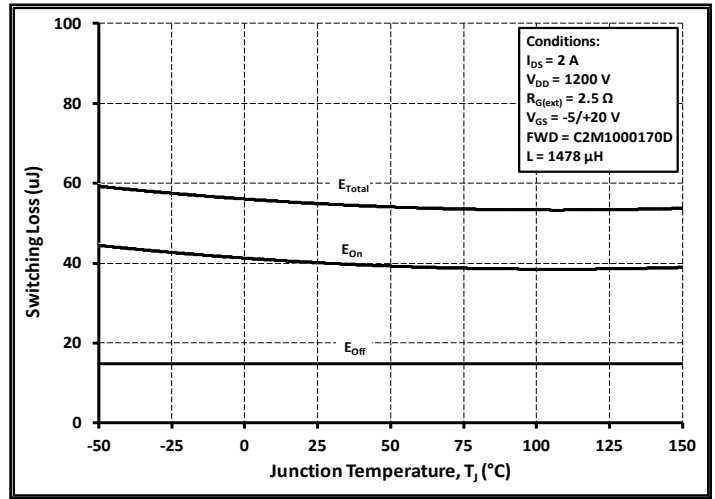


Figure 26. Clamped Inductive Switching Energy vs. Temperature

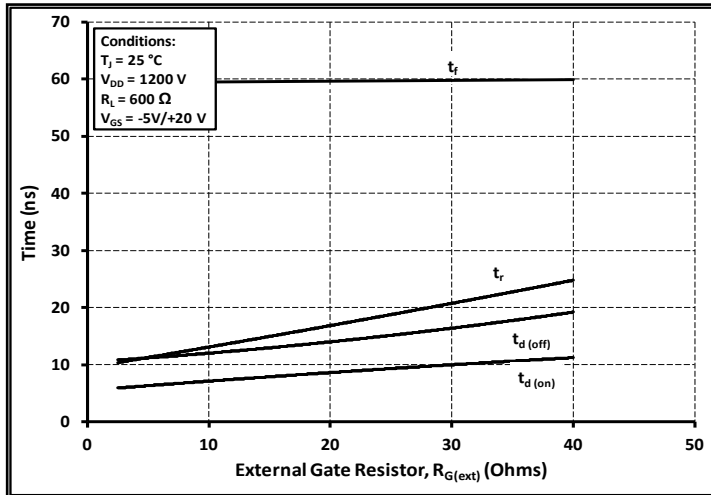


Figure 27. Switching Times vs.  $R_{G(ext)}$

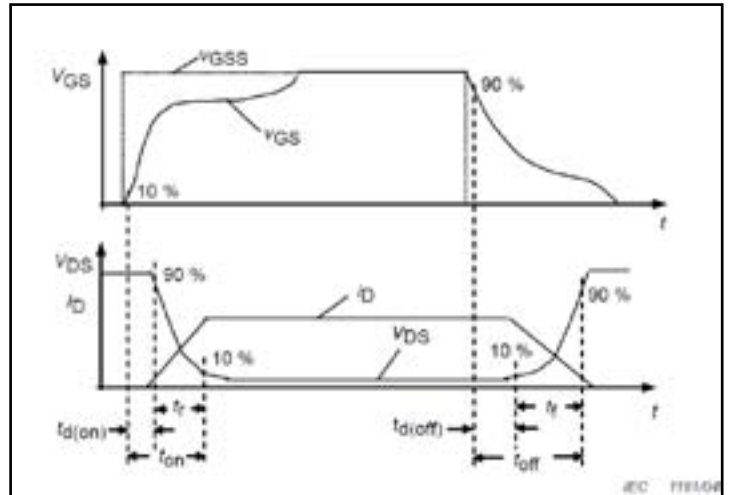


Figure 28. Switching Times Definition

## Test Circuit Schematic

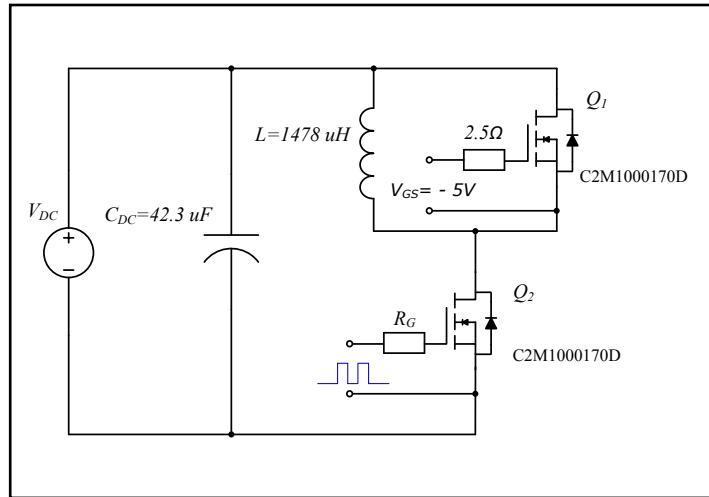


Figure 29. Clamped Inductive Switching Waveform Test Circuit

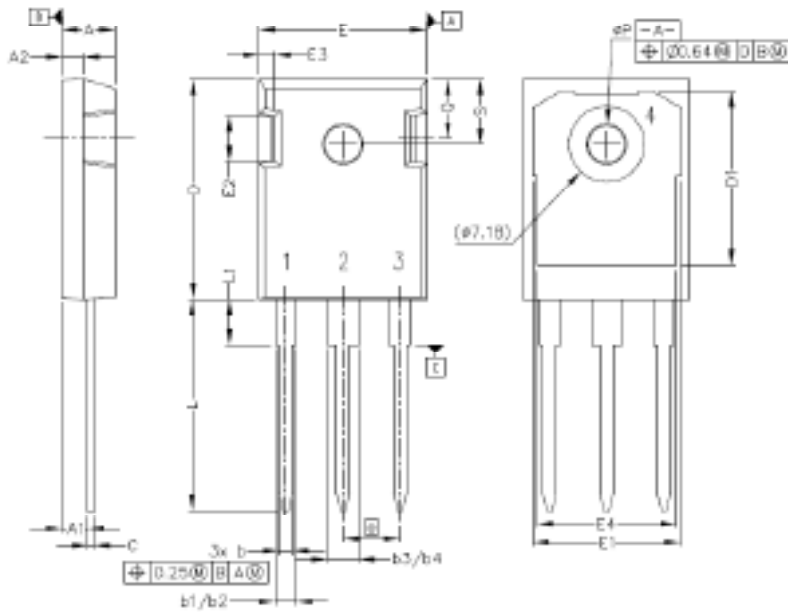
## ESD Ratings

ESD Test	Total Devices Sampled	Resulting Classification
ESD-HBM	All Devices Passed 4000V	3A (>4000V)
ESD-MM	All Devices Passed 200V	A (>200V)
ESD-CDM	All Devices Passed 1000V	IV (>1000V)



## Package Dimensions

### Package TO-247-3

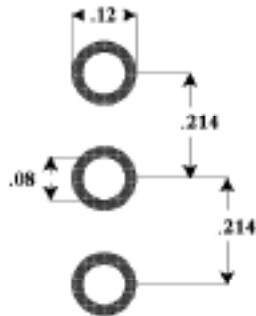


#### Pinout Information:

- Pin 1 = Gate
- Pin 2, 4 = Drain
- Pin 3 = Source

POS	Inches		Millimeters	
	Min	Max	Min	Max
A	.190	.205	4.83	5.21
A1	.090	.100	2.29	2.54
A2	.075	.085	1.91	2.16
b	.042	.052	1.07	1.33
b1	.075	.095	1.91	2.41
b2	.075	.085	1.91	2.16
b3	.113	.133	2.87	3.38
b4	.113	.123	2.87	3.13
c	.022	.027	0.55	0.68
D	.019	.031	20.60	21.10
D1	.090	.095	16.25	17.65
D2	.037	.048	0.95	1.25
E	.620	.635	15.75	16.13
E1	.516	.557	13.10	14.15
E2	.145	.201	3.68	5.18
E3	.039	.075	1.00	1.90
E4	.407	.529	12.38	13.43
e	.234 BSC		5.44 BSC	
N	3		3	
L	.760	.800	19.81	20.32
L1	.161	.173	4.18	4.40
BP	.138	.144	3.51	3.65
Q	.216	.236	5.49	6.00
S	.238	.248	6.04	6.30
T	9°	11°	9°	11°
U	9°	11°	9°	11°
V	2°	0°	2°	0°
W	2°	0°	2°	0°

## Recommended Solder Pad Layout



TO-247-3

Part Number	Package	Marking
C2M1000170D	TO-247-3	C2M1000170

## Notes

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- **RoHS Compliance**  
The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2011/65/EC (RoHS2), as implemented January 2, 2013. RoHS Declarations for this product can be obtained from your Cree representative or from the Product Documentation sections of [www.cree.com](http://www.cree.com).
- **REACH Compliance**  
REACH substances of high concern (SVHCs) information is available for this product. Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, please contact a Cree representative to insure you get the most up-to-date REACH SVHC Declaration. REACH banned substance information (REACH Article 67) is also available upon request.
- This product has not been designed or tested for use in, and is not intended for use in, applications implanted into the human body nor in applications in which failure of the product could lead to death, personal injury or property damage, including but not limited to equipment used in the operation of nuclear facilities, life-support machines, cardiac defibrillators or similar emergency medical equipment, aircraft navigation or communication or control systems, air traffic control systems.

## Related Links

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- **C2M PSPICE Models:** <http://wolfspeed.com/power/tools-and-support>
- **SiC MOSFET Isolated Gate Driver reference design:** <http://wolfspeed.com/power/tools-and-support>
- **SiC MOSFET Evaluation Board:** <http://wolfspeed.com/power/tools-and-support>
- **60W Auxiliary power supply reference design:** <http://wolfspeed.com/power/tools-and-support>